

# Comparison graph

4H-SiCウエハを“Scribe & Break”とダイシングで切断加工し比較しました。  
( □5mm、表面:Si面)

## Scribe & Break

### Number of pieces

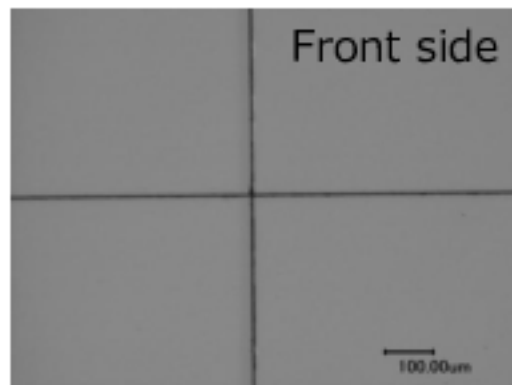
4inch-Wafer

□5mm : x1.08

□3mm : x1.14

□1mm : x1.30

(Dicing ratio)



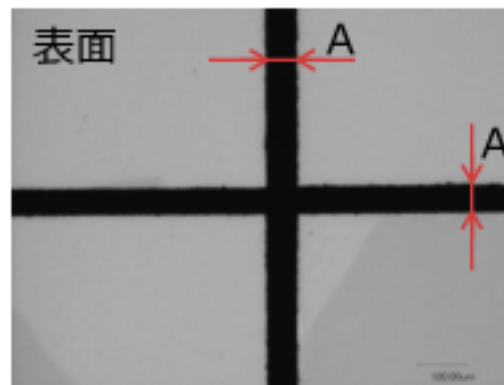
### Speed

Scribing : 100mm/s

### Processing Environment

研削水・洗浄なし(Dry)

## Dicing



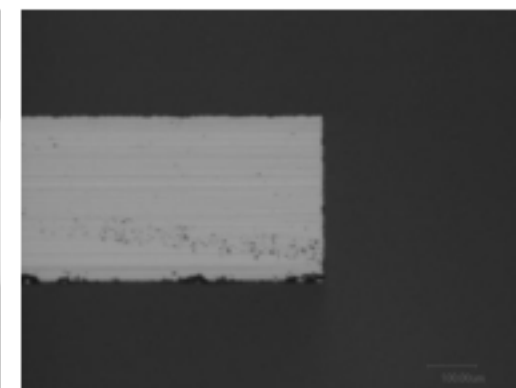
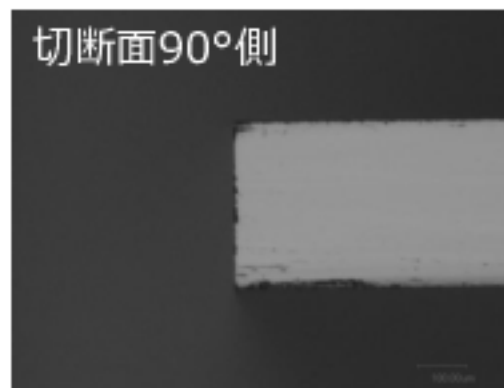
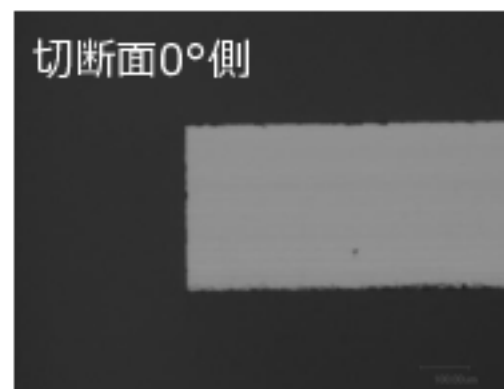
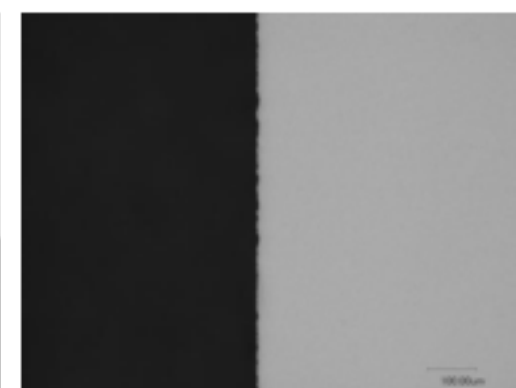
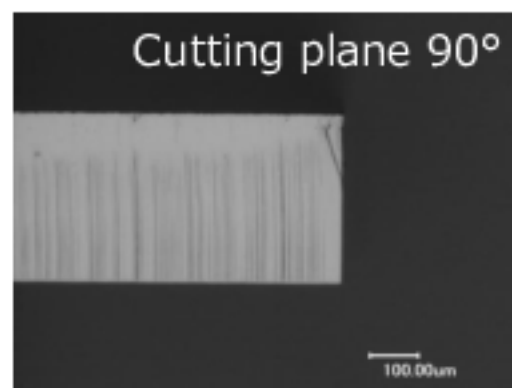
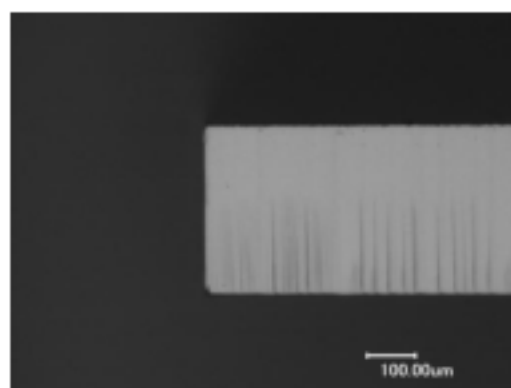
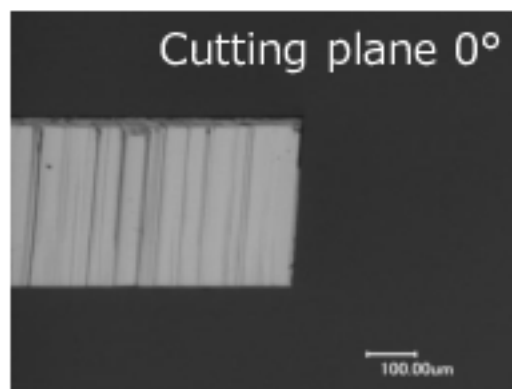
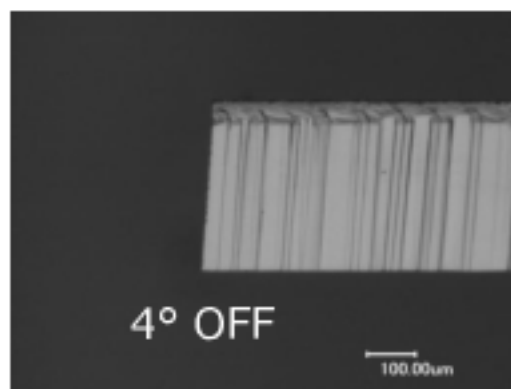
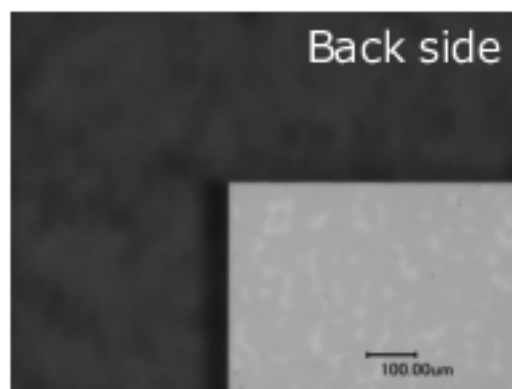
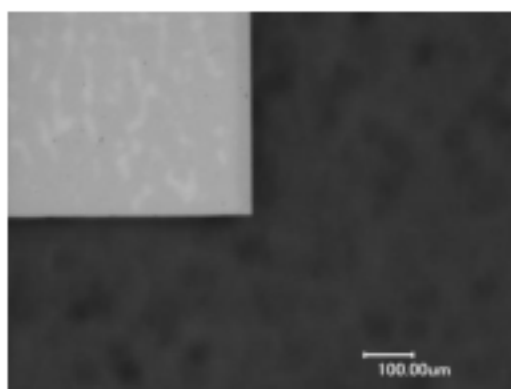
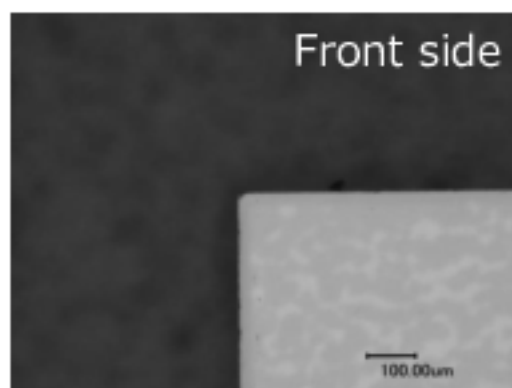
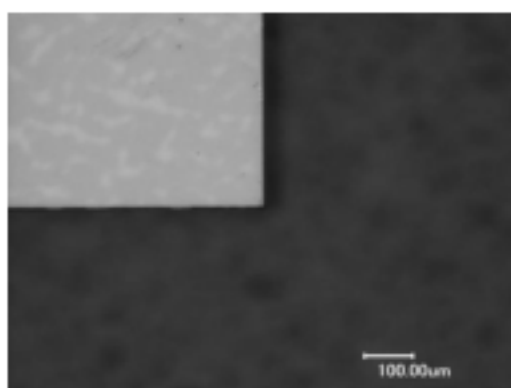
A) 切り代 (kerf-loss)  
: 60um

### 速度

Dicing : 3mm/s

### 加工環境

研削水・洗浄あり(Wet)



ご質問、ご不明点は下記までお問い合わせください。  
合同会社ブリマテック  
Mail : info@brimatec.net